

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16131	
1.3 Title of PCN	HHGrace Wuxi (China) additional source for STM32H562x/563x and STM32H573x in E40 technology.	
1.4 Product Category	STM32H562x, STM32H563x and STM32H573x	
1.5 Issue date	2026-03-26	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	HHGrace Wuxi (China)

4. Description of change

	Old	New
4.1 Description	Front-end sources for STM32H562x, STM32H563x and STM32H573x - ST CROLLES 300 (France)	Front-end sources for STM32H562x, STM32H563x and STM32H573x - ST CROLLES 300 (France) existing source - HHGrace (China) additional source
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No change	

5. Reason / motivation for change

5.1 Motivation	Second source introduction
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible in the marking. Please refer to PCN 16131_Additional information.pdf document for further details.
------------------------	--

7. Timing / schedule

7.1 Date of qualification results	2026-07-10
7.2 Intended start of delivery	2026-07-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16131 MDRF-GPAM-RER2609 PCN16131 - HHGrace Wuxi (China) E40 - PLAN.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-03-26

9. Attachments (additional documentations)

16131 Public product.pdf
 16131 MDRF-GPAM-RER2609 PCN16131 - HHGrace Wuxi (China) E40 - PLAN.pdf
 16131 _Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H562AGI6	
	STM32H562AII6	
	STM32H562IGK6	
	STM32H562IGT6	
	STM32H562IIK6	
	STM32H562IIT6	
	STM32H562RGT6	
	STM32H562RGV6	
	STM32H562RIT6	
	STM32H562RIV6	
	STM32H562VGT6	
	STM32H562VIT6	
	STM32H562ZGT6	
	STM32H562ZIT6	
	STM32H563AGI6	
	STM32H563AII3Q	
	STM32H563AII6	
	STM32H563IGK6	
	STM32H563IGT6	
	STM32H563IIK3Q	
	STM32H563IIK6	
	STM32H563IIT3Q	
	STM32H563IIT6	
	STM32H563RGT6	
	STM32H563RGV6	
	STM32H563RIT6	
	STM32H563RIV6	
	STM32H563VGT6	
	STM32H563VIT3Q	
	STM32H563VIT6	
	STM32H563ZGT6	
	STM32H563ZIT3Q	
	STM32H563ZIT6	
	STM32H573AII3Q	
	STM32H573AII6	
	STM32H573IIK3Q	
	STM32H573IIK6	
	STM32H573IIT3Q	
	STM32H573IIT6	
	STM32H573RIT6	
	STM32H573RIV6	
	STM32H573VIT3Q	
	STM32H573VIT6	
	STM32H573ZIT3Q	

	STM32H573ZIT6	
--	---------------	--

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved